

PC364NJ0000F Series

Mini-Flat Package High CMR, AC Input, Low Input Current Type Photocoupler



■ Description

PC364NJ0000F Series contains an IRED optically coupled to a phototransistor.

AC input and Low input current type.

It is packaged in a 4-pin mini-flat.

Input-output isolation voltage(rms) is 3.75kV.

Collector-emitter voltage is 80V and CTR is 50% to 400% at input current of ±0.5mA.

■ Features

- 1. 4-pin Mini-flat package
- 2. Double transfer mold package (Ideal for Flow Soldering)
- 3. AC input type
- 4. Low input current type (I_F=±0.5mA)
- 5. High collector-emitter voltage (V_{CEO}: 80V)
- High noise immunity due to high common mode rejection voltage (CMR: MIN. 10kV/μs)
- 7. High isolation voltage between input and output (V_{iso(rms)}: 3.75kV)
- 8. RoHS directive compliant

■ Agency approvals/Compliance

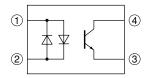
- Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC364)
- 2. Package resin: UL flammability grade (94V-0)

Applications

- 1. Programmable controllers
- 2. Facsimiles
- 3. Telephones



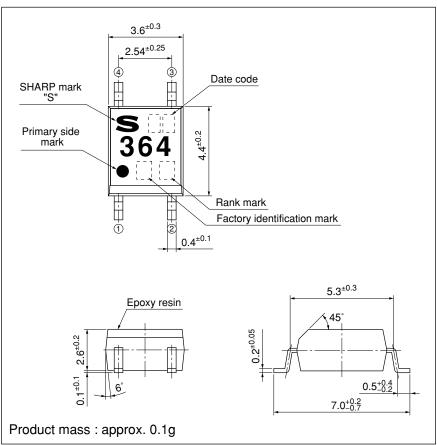
■ Internal Connection Diagram



- 1) Anode/Cathode
- ② Cathode/Anode
- 3 Emitter
- 4 Collector

■ Outline Dimensions

(Unit: mm)



Plating material: SnCu (Cu: TYP. 2%)



Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	A	2002	P	January	1	
1991	В	2003	R	February	2	
1992	С	2004	S	March	3	
1993	D	2005	T	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	X	August	8	
1998	K	2010	A	September	9	
1999	L	2011	В	October	0	
2000	M	2012	С	November	N	
2001	N	:	:	December	D	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin	
no mark	Ionon	
	Japan	
	Indonesia	
_	China	

^{*} This factory marking is for identification purpose only.

Please Contact the local SHARP sales reprsentative to see the actual status of the production.

Rank mark

Refer to the Model Line-up table



■ Absolute Maximum Ratings

	Absolute Maximum Ratings $(T_a=25^{\circ}C)$						
	Parameter	Symbol	Rating	Unit			
_	Forward current	I_F	±10	mA			
Input	*1 Peak forward current	I_{FM}	±200	mA			
Т	Power dissipation	P	15	mW			
	Collector-emitter voltage	V _{CEO}	80	V			
Output	Emitter-collector voltage	V _{ECO}	6	V			
Out	Collector current	I_C	50	mA			
	Collector power dissipation	P _C	150	mW			
Total power dissipation		P _{tot}	170	mW			
	Operating temperature	Topr	-30 to +100	°C			
Storage temperature		T_{stg}	-40 to +125	°C			
*2 Isolation voltage		V _{iso (rms)}	3.75	kV			
*3 Soldering temperature		T _{sol}	260	°C			

^{*1} Pulse width≤100µs, Duty ratio: 0.001 *2 40 to 60%RH, AC for 1 minute, f=60Hz

■ Electro-optical Characteristics

 $(T_a=25^{\circ}C)$

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input Forward voltage Terminal capacitance		V_F	I _F =±10mA	-	1.2	1.4	V	
		C_{t}	V=0, f=1kHz	-	30	250	pF	
	Collector dark	current	I_{CEO}	$V_{CE} = 50V, I_{F} = 0$	_	1	100	nA
Output	Collector-emitter brea	kdown voltage	BV_{CEO}	$I_{C}=0.1 \text{mA}, I_{F}=0$	80	ı	-	V
Emitter-collector breakdown voltage		$\mathrm{BV}_{\mathrm{ECO}}$	$I_{E}=10\mu A, I_{F}=0$	6	ı	-	V	
Collector current Collector-emitter saturation volt		ent	I_{C}	$I_F=\pm 0.5$ mA, $V_{CE}=5$ V	0.25	ı	2.0	mA
		ıration voltage	V _{CE (sat)}	$I_F=\pm 10mA$, $I_C=1mA$	ı	ı	0.2	V
	Isolation resistance		R_{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10^{11}	-	Ω
	Transfer Floating capacitance		C_{f}	V=0, $f=1MHz$	-	0.6	1.0	pF
charac- teristics	Response time	Rise time	$t_{\rm r}$	V_{CE} =2V, I_C =2mA, R_L =100 Ω	ı	4	18	μs
		Fall time	t_{f}		-	3	18	μs
	Common mode rejection voltage		CMR	$\begin{split} T_{a} = & 25^{\circ}C, R_{L} = & 470\Omega, V_{CM} = 1.5 kV(peak) \\ I_{F} = & 0, V_{CC} = & 9V, V_{np} = 100 mV \end{split}$	10	_	_	kV/μs

^{*3} For 10s



■ Model Line-up

D 1	Tap	oing	D l l-	I _C [mA]	
Package	3 000 pcs / reel	750 pcs / reel	Rank mark	$(I_F=\pm 0.5 \text{mA}, V_{CE}=5 \text{V}, T_a=25 ^{\circ}\text{C})$	
Model No.	PC364NJ0000F	PC364NTJ000F	with or without	0.25 to 2.0	
Model No.	PC364N1J000F	PC364N1TJ00F	A	0.5 to 1.5	

Please contact a local SHARP sales representative to inquire about production status.



Fig.1 Test Circuit for Common Mode Rejection Voltae

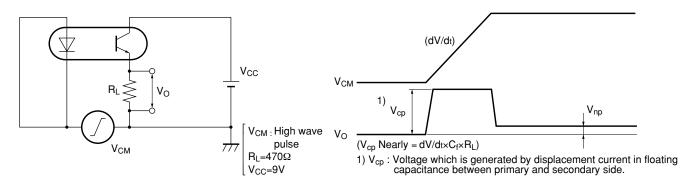


Fig.2 Forward Current vs. Ambient Temperature

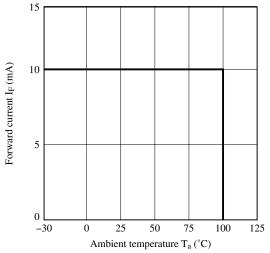


Fig.4 Collector Power Dissipation vs. Ambient Temperature

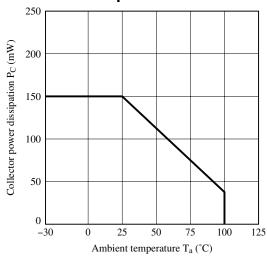


Fig.3 Diode Power Dissipation vs. Ambient Temperature

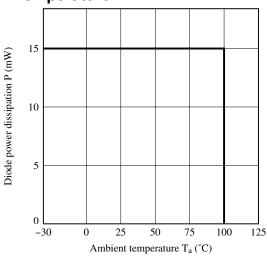


Fig.5 Total Power Dissipation vs. Ambient Temperature

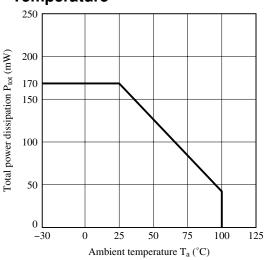




Fig.6 Peak Forward Current vs. Duty Ratio

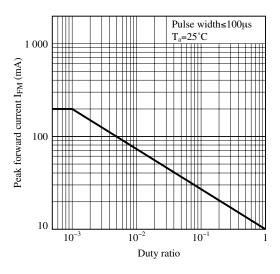


Fig.8 Current Transfer Ratio vs. Forward Current

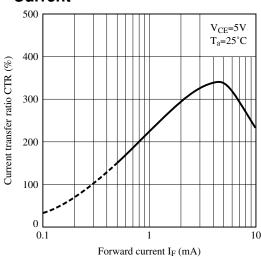


Fig.10 Relative Current Transfer Ratio vs.
Ambient Temperature

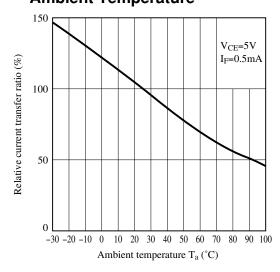


Fig.7 Forward Current vs. Forward Voltage

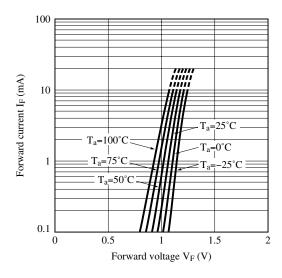


Fig.9 Collector Current vs. Collector-emitter Voltage

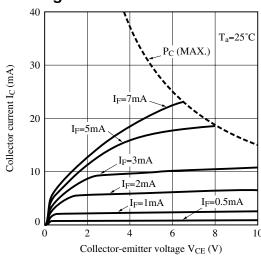


Fig.11 Collector - emitter Saturation Voltage vs. Ambient Temperature

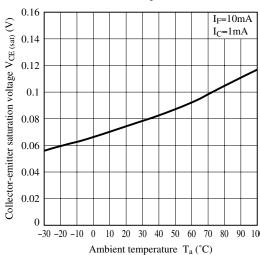




Fig.12 Collector Dark Current vs. Ambient Temperature

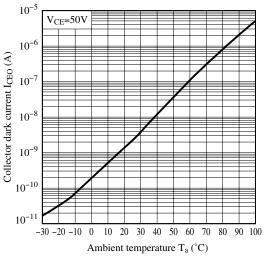


Fig.14 Response Time vs. Load Resistance (Saturation region)

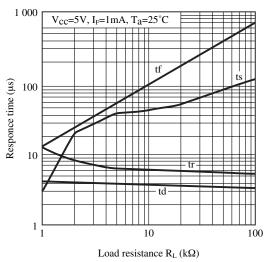


Fig.16 Frequency Response

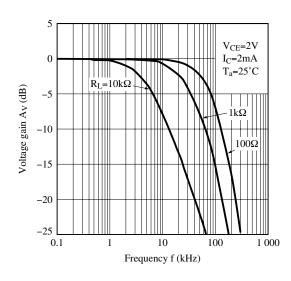


Fig.13 Response Time vs. Load Resistance (Active region)

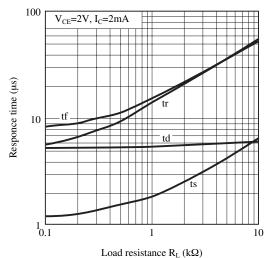
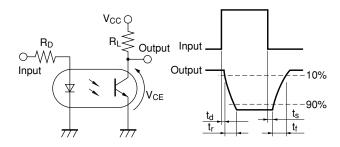
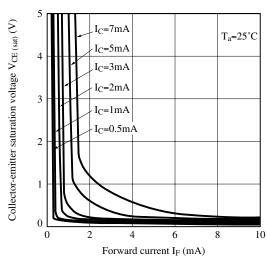


Fig.15 Test Circuit for Response Time



Please refer to the conditions in Fig.13 and Fig. 14

Fig.17 Collector-emitter Saturation Voltage vs. Forward Current



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



■ Design Considerations

Design guide

While operating at I_F<0.5mA, CTR variation may increase.

Please make design considering this fact.

In case that some sudden big noise caused by voltage variation is provided between primary and secondary terminals of photocoupler some current caused by it is floating capacitance may be generated and result in false operation since current may go through IRED or current may change.

If the photocoupler may be used under the circumstances where noise will be generated we recommend to use the bypass capacitors at the both ends of IRED.

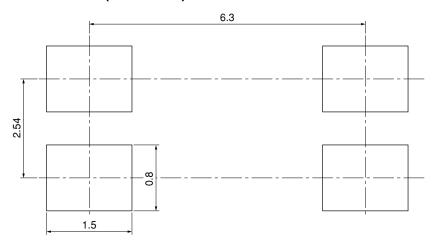
This product is not designed against irradiation and incorporates non-coherent IRED.

Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

Recommended Foot Print (reference)



(Unit:mm)

[☆] For additional design assistance, please review our corresponding Optoelectronic Application Notes.



■ Manufacturing Guidelines

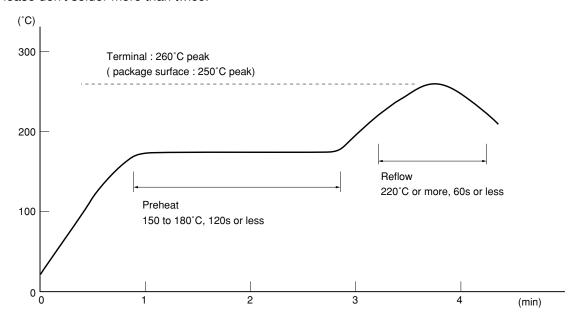
Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



Flow Soldering:

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



Cleaning instructions

Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3 minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



■ Package specification

● Tape and Reel package

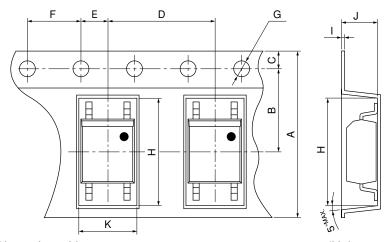
1. 3 000pcs/reel Package materials

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

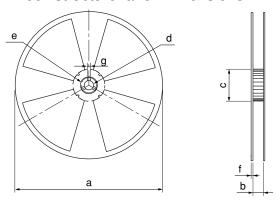
Reel: PS

Carrier tape structure and Dimensions



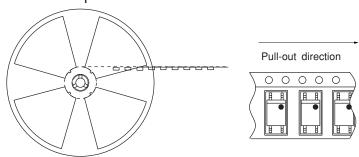
Dimensions List (Unit: mm						<u>Jnit : mm)</u>
A	В	C	D	Е	F	G
12.0±0.3	5.5 ^{±0.1}	1.75 ^{±0.1}	8.0 ^{±0.1}	2.0 ^{±0.1}	4.0 ^{±0.1}	φ1.5+0.1
Н	I	J	K			
7.4 ^{±0.1}	0.3 ^{±0.05}	3.1 ^{±0.1}	4.0 ^{±0.1}			

Reel structure and Dimensions



Dimensio	ns List	(Unit: mm)		
a	b	с	d	
370	370 13.5±1.5		13±0.5	
e	f	g		
21 ^{±1.0}	2.0±0.5	2.0±0.5		

Direction of product insertion



[Packing: 3 000pcs/reel]



Package materials

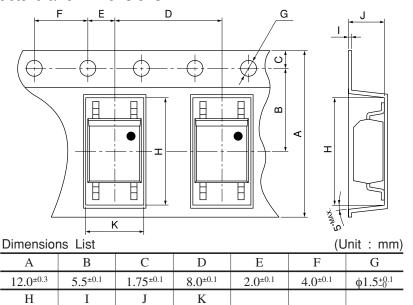
2. 750 pcs / reel

Carrier tape: A-PET (with anti-static material)

Cover tape: PET (three layer system)

Reel: PS

Carrier tape structure and Dimensions



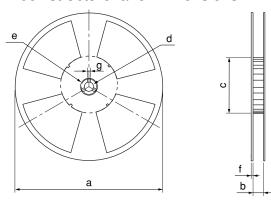
 $4.0^{\pm0.1}$

Reel structure and Dimensions

 $7.4^{\pm0.1}$

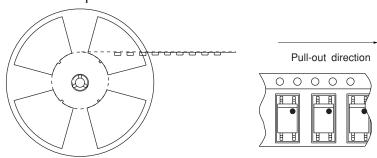
0.3±0.05

3.1±0.1



Dimensio	ns List	(Unit: mm)		
a	b	с	d	
180	180 13.5±1.5		13±0.5	
e	f	g		
21 ^{±1.0}	2.0±0.5	2.0±0.5		

Direction of product insertion



[Packing: 750pcs/reel]



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- --- Alarm equipment
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[E197] Sheet No.: D2-A00702FEN